

Abstract

An object of the present invention is to provide a copper foil having excellent adhesion to an etching resist layer, without performing physical polishing such as buffing in pre-treatment of an etching process to form a circuit from the copper foil. To attain the object, in electroforming, a titanium material having a grain size number of 6.0 or more is employed as a copper deposition surface of the rotating drum cathode, and glue and/or gelatin is added in an amount of 0.2-20 mg/l to a copper sulfate solution, thereby producing a drum foil. An electrodeposited copper foil obtained from the drum foil, wherein 20% or more of the crystals present in a shiny side surface of the electrodeposited copper foil have a twin-crystal structure, is used for producing copper-clad laminates.